

40V NPN SMALL SIGNAL TRANSISTOR IN SOT523

Features

- BV_{CEO} > 40V
- I_C = 600mA Collector Current
- Epitaxial Planar Die Construction
- Ultra-Small Surface Mount Package
- Complementary PNP Type: MMBT2907AT
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

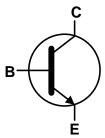
Mechanical Data

- Case: SOT523
- Case Material: Molded Plastic. "Green" Molding Compound.
 UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 (a3)
- Weight: 0.002 grams (Approximate)

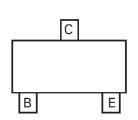








Device Symbol



Pin-out Top View

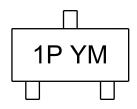
Ordering Information (Note 4)

Product	Status	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
MMBT2222AT-7-F	Active	AEC-Q101	1P	7	8	3,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



1P = Product Type Marking Code YM = Date Code Marking Y or \overline{Y} = Year (ex: F = 2018) M or \overline{M} = Month (ex: 9 = September)

Date Code Key

Year	2018	2	019	2020	2021	2022	2023	2024	4 20	25 2	2026	2027	2028
Code	F		G	Н		J	K	L	٨	Л	N	0	Р
Month	1	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code		1	2	3	4	5	6	7	8	9	0	N	D



Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	75	V
Collector-Emitter Voltage	V_{CEO}	40	V
Emitter-Base Voltage	V_{EBO}	6	V
Collector Current	Ic	600	mA

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	Pd	150	mW
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	833	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

ESD Ratings (Note 6)

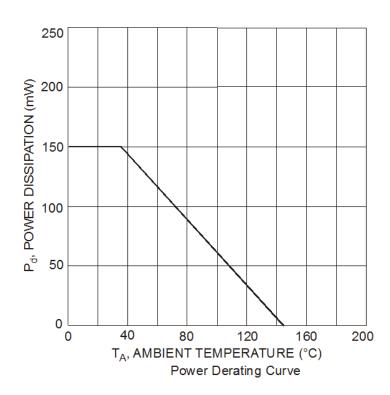
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	С

Notes:

- 5. For a device mounted with the collector lead on minimum recommended pad layout 1oz copper that is on a single-sided 1.6mm FR-4 PCB; device is measured under still air conditions whilst operating in a steady-state.

 6. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

Thermal Characteristics and Derating Information



April 2018

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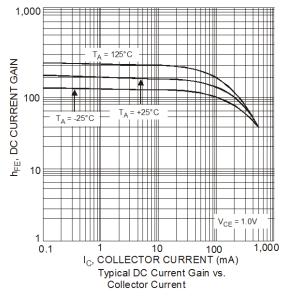
Electrical Characteristics (@ $T_A = +25$ °C, unless otherwise specified.)

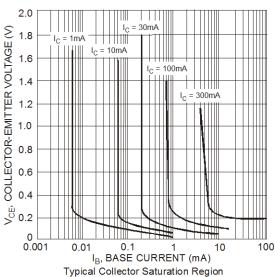
Characteristic	Symbol	Min	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)					
Collector-Base Breakdown Voltage	BV _{CBO}	75	_	V	$I_C = 10\mu A, I_E = 0$
Collector-Emitter Breakdown Voltage	BV_{CEO}	40	_	V	$I_C = 1mA, I_B = 0$
Emitter-Base Breakdown Voltage	BV _{EBO}	6	_	V	$I_E = 10\mu A, I_C = 0$
Collector Cutoff Current	I _{CEX}	_	10	nA	$V_{CE} = 60V$, $V_{EB(OFF)} = 3V$
Base Cutoff Current	I_{BL}	_	20	nA	$V_{CE} = 60V$, $V_{EB(OFF)} = 3V$
ON CHARACTERISTICS (Note 7)					
		35	_		$I_C = 100 \mu A$, $V_{CE} = 10 V$
		50	_		$I_C = 1.0 \text{mA}, V_{CE} = 10 \text{V}$
DC Current Gain	h _{FE}	75	_	_	$I_C = 10mA, V_{CE} = 10V$
		100	300		$I_C = 150 \text{mA}, V_{CE} = 10 \text{V}$
		40	_		$I_C = 500 \text{mA}, V_{CE} = 10 \text{V}$
Collector-Emitter Saturation Voltage	V _{CE(SAT)}		0.3	V	$I_C = 150 \text{mA}, I_B = 15 \text{mA}$
Concolor Emilior Calaration Voltage	VCE(SAT)		1.0	,	$I_C = 500 \text{mA}, I_B = 50 \text{mA}$
Base-Emitter Saturation Voltage	V _{BE(SAT)}	0.6	1.2	V	$I_C = 150 \text{mA}, I_B = 15 \text{mA}$
· ·	V BE(SAT)		2.0	v	$I_C = 500 \text{mA}, I_B = 50 \text{mA}$
SMALL SIGNAL CHARACTERISTICS	1	1	1	1	
Output Capacitance	C _{obo}	_	8	pF	$V_{CB} = 10V, f = 1.0MHz, I_{E} = 0$
Input Capacitance	C _{ibo}	_	30	pF	$V_{EB} = 0.5V$, $f = 1.0MHz$, $I_{C} = 0$
Input Impedance	h _{ie}	0.25	1.25	kΩ	
Voltage Feedback Ratio	h _{re}	_	4.0	x 10 ⁻⁴	$V_{CE} = 10V, I_{C} = 10mA,$
Small Signal Current Gain	h _{fe}	75	375	_	f = 1.0MHz
Output Admittance	h _{oe}	25	200	μS	
Current Gain-Bandwidth Product	f _T	300	_	MHz	$V_{CE} = 20V, I_{C} = 20mA,$ f = 100MHz
SWITCHING CHARACTERISTICS					
Delay Time	t _D	_	10	ns	V _{CC} = 30V, I _C = 150mA,
Rise Time	t _R		25	ns	$V_{BE(OFF)} = -0.5V, I_{B1} = 15mA$
Storage Time	ts	_	225	ns	V _{CC} = 30V, I _C = 150mA
Fall Time	t _F		60	ns	$I_{B1} = -I_{B2} = 15mA$

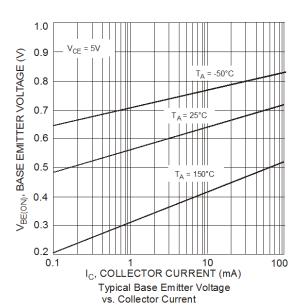
Notes: 7. Measured under pulsed conditions. Pulse width \leq 300 μ s. Duty cycle \leq 2%.

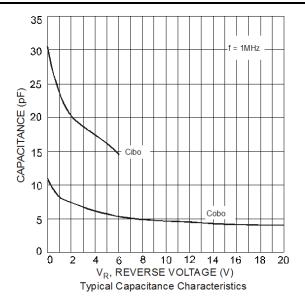


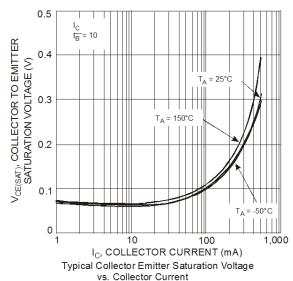
Typical Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)











1,000

V_{CE} = 5V

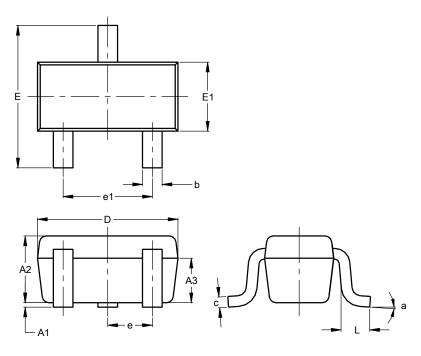
Typical Gain Bandwidth Product vs. Collector Current



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT523

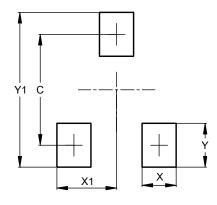


SOT523							
Dim	Min	Max	Тур				
A1	0.00	0.10	0.05				
A2	0.60	0.80	0.75				
А3	0.45	0.65	0.50				
b	0.15	0.30	0.22				
С	0.10	0.20	0.12				
D	1.50	1.70	1.60				
Е	1.45	1.75	1.60				
E1	0.75	0.85	0.80				
е		0.50 BS	С				
e1	0.90	1.10	1.00				
L	0.20	0.40	0.33				
а	0°		8°				
All Dimensions in mm							

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT523



Dimensions	Value
Dilliensions	(in mm)
С	1.29
Х	0.40
X1	0.70
Υ	0.51
Y1	1.80



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